CMXD2004TO

SURFACE MOUNT TRIPLE ISOLATED OPPOSING HIGH VOLTAGE SILICON SWITCHING DIODES





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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMXD2004TO consists of three (3) Isolated High Voltage Silicon Switching Diodes arranged in an alternating configuration in a SUPERmini SOT-26 surface mount package, and designed for high voltage switching applications. This device can be configured as a 900V switching diode. See optional mounting pad configuration.

MARKING CODE: X04TO

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	V_{R}	240	V
Peak Repetitive Reverse Voltage	V_{RRM}	300	V
Average Forward Current	IO	200	mA
Continuous Forward Current	IF	225	mA
Peak Repetitive Forward Current	I _{FRM}	625	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	4.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	350	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ.ΙΑ	357	°C/W

$\textbf{ELECTRICAL CHARACTERISTICS PER DIODE:} \ (T_{\mbox{\scriptsize A}} = 25 \ ^{\circ}\mbox{C unless otherwise noted})$

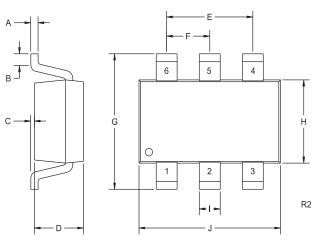
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{R}	V _R =240V		100	nA
I_{R}	V _R =240V, T _A =150°C		100	μΑ
BV_R	I _R =100μA	300		V
V_{F}	I _F =100mA		1.0	V
C_T	V_R =0, f=1.0MHz		5.0	pF
t _{rr}	$I_F = I_R = 30 \text{mA}, I_{rr} = 3.0 \text{mA}, R_L = 100 \Omega$		50	ns

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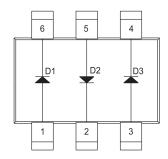
SOT 26 CASE - MECHANICAL OUTLINE



DIMENSIONS								
	INCHES		MILLIMETERS					
SYMBOL	MIN	MAX	MIN	MAX				
Α	0.004	0.007	0.11	0.19				
В	0.016	-	0.40	-				
С	-	0.004	-	0.10				
D	0.039	0.047	1.00	1.20				
E	0.074	0.075	1.88	1.92				
F	0.037	0.038	0.93	0.97				
G	0.102	0.118	2.60	3.00				
Н	0.059	0.067	1.50	1.70				
ı	0.016		0.41					
J	0.110	0.118	2.80	3.00				

SOT-26 (REV: R2)

PIN CONFIGURATION



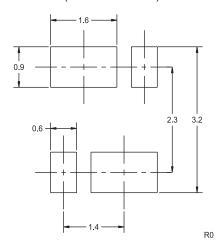
LEAD CODE:

- 1) Anode D1
- 2) Cathode D2
- 3) Anode D3
- 4) Cathode D3
- 5) Anode D2
- 6) Cathode D1

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OPTIONAL MOUNTING PADS For 900V Series Configuration

(Dimensions in mm)



R2 (12-February 2010)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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